Title: Datasheet for MCP6291, MCP6294 Customer Contact: PCN Manager Dept: Quality Services Change Type: Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(5) is being updated as summarized below. The following change history provides further details. Wafer Sum Process MCP6291, MCP6292, MCP6294 Changes from Revision B (April 2018) to Revision C Page Objected SOT-23 package preview notation in Device Information table Added DCK package information table Added DCK package preview notation for Pin Configuration and Functions section 4 Added DCK package preview notation for Pin Configuration and Functions section Added DCK package for memal information	PCN Number:	CN Number: 20190508000 PCN Date: May 9, 2019							
Customer Contact: PCN. Manager Dept: Quality Services Charge Type:									
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